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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	12
Program Memory Size	768B (512 x 12)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	25 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	20-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f54-e-ss

1.0 GENERAL DESCRIPTION

The PIC16F5X from Microchip Technology is a family of low-cost, high-performance, 8-bit, fully static, Flash-based CMOS microcontrollers. It employs a RISC architecture with only 33 single-word/single-cycle instructions. All instructions are single cycle except for program branches which take two cycles. The PIC16F5X delivers performance an order of magnitude higher than its competitors in the same price category. The 12-bit wide instructions are highly symmetrical resulting in 2:1 code compression over other 8-bit microcontrollers in its class. The easy-to-use and easy-to-remember instruction set reduces development time significantly.

The PIC16F5X products are equipped with special features that reduce system cost and power requirements. The Power-on Reset (POR) and Device Reset Timer (DRT) eliminate the need for external Reset circuitry. There are four oscillator configurations to choose from, including the power-saving LP (Low Power) oscillator and cost saving RC oscillator. Power-saving Sleep mode, Watchdog Timer and code protection features improve system cost, power and reliability.

The PIC16F5X products are supported by a full-featured macro assembler, a software simulator, a low-cost development programmer and a full featured programmer. All the tools are supported on IBM® PC and compatible machines.

1.1 Applications

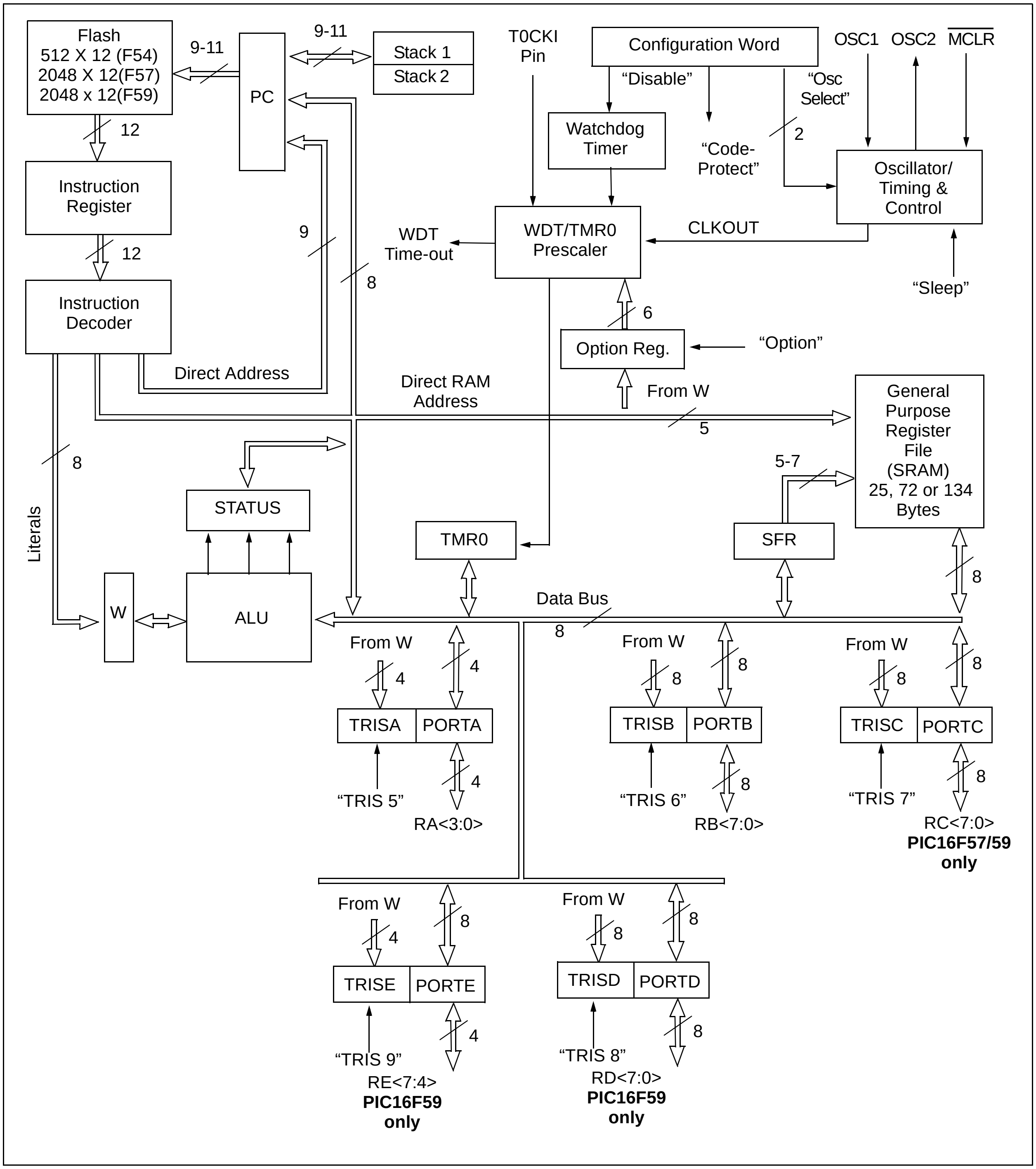
The PIC16F5X series fits perfectly in applications ranging from high-speed automotive and appliance motor control to low-power remote transmitters/receivers, pointing devices and telecom processors. The Flash technology makes customizing application programs (transmitter codes, motor speeds, receiver frequencies, etc.) extremely fast and convenient. The small footprint packages, for through hole or surface mounting, make this microcontroller series perfect for applications with space limitations. Low-cost, low-power, high performance, ease of use and I/O flexibility make the PIC16F5X series very versatile, even in areas where no microcontroller use has been considered before (e.g., timer functions, replacement of “glue” logic in larger systems, co-processor applications).

TABLE 1-1: PIC16F5X FAMILY OF DEVICES

Features	PIC16F54	PIC16F57	PIC16F59
Maximum Operation Frequency	20 MHz	20 MHz	20 MHz
Flash Program Memory (x12 words)	512	2K	2K
RAM Data Memory (bytes)	25	72	134
Timer Module(s)	TMR0	TMR0	TMR0
I/O Pins	12	20	32
Number of Instructions	33	33	33
Packages	18-pin DIP, SOIC; 20-pin SSOP	28-pin DIP, SOIC; 28-pin SSOP	40-pin DIP, 44-pin TQFP

Note: All PIC® Family devices have Power-on Reset, selectable Watchdog Timer, selectable code-protect and high I/O current capability.

FIGURE 2-1: PIC16F5X SERIES BLOCK DIAGRAM



4.0 OSCILLATOR CONFIGURATIONS

4.1 Oscillator Types

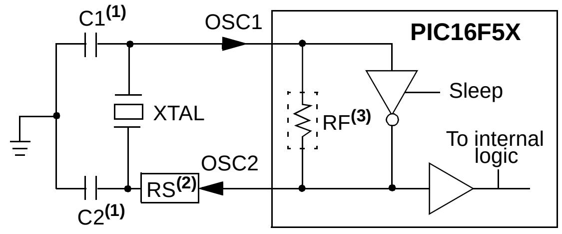
The PIC16F5X devices can be operated in four different oscillator modes. The user can program two Configuration bits (FOSC1:FOSC0) to select one of these four modes:

- LP: Low-power Crystal
- XT: Crystal/Resonator
- HS: High-speed Crystal/Resonator
- RC: Resistor/Capacitor

4.2 Crystal Oscillator/Ceramic Resonators

In XT, LP or HS modes, a crystal or ceramic resonator is connected to the OSC1/CLKIN and OSC2/CLKOUT pins to establish oscillation (Figure 4-1). The PIC16F5X oscillator design requires the use of a parallel cut crystal. Use of a series cut crystal may give a frequency outside of the crystal manufacturers specifications. When in XT, LP or HS modes, the device can have an external clock source drive the OSC1/CLKIN pin (Figure 4-2).

FIGURE 4-1: CRYSTAL/CERAMIC RESONATOR OPERATION (HS, XT OR LP OSC CONFIGURATION)



Note 1: See Capacitor Selection tables for recommended values of C1 and C2.

2: A series resistor (RS) may be required.

3: RF varies with the Oscillator mode chosen (approx. value = 10 MΩ).

FIGURE 4-2: EXTERNAL CLOCK INPUT OPERATION (HS, XT OR LP OSC CONFIGURATION)

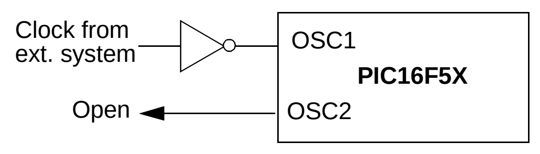


TABLE 4-1: CAPACITOR SELECTION FOR CERAMIC RESONATORS

Osc Type	Resonator Freq.	Cap. Range C1	Cap. Range C2
XT	455 kHz 2.0 MHz 4.0 MHz	68-100 pF 15-33 pF 10-22 pF	68-100 pF 15-33 pF 10-22 pF
HS	8.0 MHz 16.0 MHz	10-22 pF 10 pF	10-22 pF 10 pF

These values are for design guidance only. Since each resonator has its own characteristics, the user should consult the resonator manufacturer for appropriate values of external components.

TABLE 4-2: CAPACITOR SELECTION FOR CRYSTAL OSCILLATOR

Osc Type	Crystal Freq.	Cap.Range C1	Cap. Range C2
LP	32 kHz(1)	15 pF	15 pF
XT	100 kHz 200 kHz 455 kHz 1 MHz 2 MHz 4 MHz	15-30 pF 15-30 pF 15-30 pF 15-30 pF 15 pF 15 pF	200-300 pF 100-200 pF 15-100 pF 15-30 pF 15 pF 15 pF
HS	4 MHz 8 MHz 20 MHz	15 pF 15 pF 15 pF	15 pF 15 pF 15 pF

Note 1: For VDD > 4.5V, C1 = C2 ≈ 30 pF is recommended.

These values are for design guidance only. Rs may be required in HS mode, as well as XT mode, to avoid overdriving crystals with low drive level specifications. Since each crystal has its own characteristics, the user should consult the crystal manufacturer for appropriate values of external components.

Note 1: This device has been designed to perform to the parameters of its data sheet. It has been tested to an electrical specification designed to determine its conformance with these parameters. Due to process differences in the manufacture of this device, this device may have different performance characteristics than its earlier version. These differences may cause this device to perform differently in your application than the earlier version of this device.

2: The user should verify that the device oscillator starts and performs as expected. Adjusting the loading capacitor values and/or the Oscillator mode may be required.

6.0 I/O PORTS

As with any other register, the I/O registers can be written and read under program control. However, read instructions (e.g., `MOVF PORTB, W`) always read the I/O pins independent of the pin's Input/Output modes. On Reset, all I/O ports are defined as input (inputs are at high-impedance), since the I/O control registers (TRISA, TRISB, TRISC, TRISD and TRISE) are all set.

6.1 PORTA

PORTA is a 4-bit I/O register. Only the low order 4 bits are used (PORTA<3:0>). The high order 4 bits (PORTA<7:4>) are unimplemented and read as '`0`'s.

6.2 PORTB

PORTB is an 8-bit I/O register (PORTB<7:0>).

6.3 PORTC

PORTC is an 8-bit I/O register (PORTC<7:0>) for the PIC16F57 and PIC16F59.

PORTC is a General Purpose Register for the PIC16F54.

6.4 PORTD

PORTD is an 8-bit I/O register (PORTD<7:0>) for the PIC16F59.

PORTD is a General Purpose Register for the PIC16F54 and PIC16F57.

6.5 PORTE

PORTE is an 4-bit I/O register for the PIC16F59. Only the high order 4 bits are used (PORTE<7:4>). The low order 4 bits (PORTE<3:0>) are unimplemented and read as '`0`'s.

PORTE is a General Purpose Register for the PIC16F54 and PIC16F57.

6.6 TRIS Registers

The output driver control registers are loaded with the contents of the W register by executing the `TRIS f` instruction. A '`1`' from a TRIS register bit puts the corresponding output driver in a High-Impedance (Input) mode. A '`0`' puts the contents of the output data latch on the selected pins, enabling the output buffer.

Note:	A read of the ports reads the pins, not the output data latches. That is, if an output driver on a pin is enabled and driven high, but the external system is holding it low, a read of the port will indicate that the pin is low.

The TRIS registers are "write-only" and are set (output drivers disabled) upon Reset.

6.7 I/O Interfacing

The equivalent circuit for an I/O port pin is shown in Figure 6-1. All ports may be used for both input and output operation. For input operations, these ports are non-latching. Any input must be present until read by an input instruction (e.g., `MOVF PORTB, W`). The outputs are latched and remain unchanged until the output latch is rewritten. To use a port pin as output, the corresponding direction control bit (in TRISA, TRISB, TRISC, TRISD and TRISE) must be cleared (= `0`). For use as an input, the corresponding TRIS bit must be set. Any I/O pin can be programmed individually as input or output.

FIGURE 6-1: EQUIVALENT CIRCUIT FOR A SINGLE I/O PIN

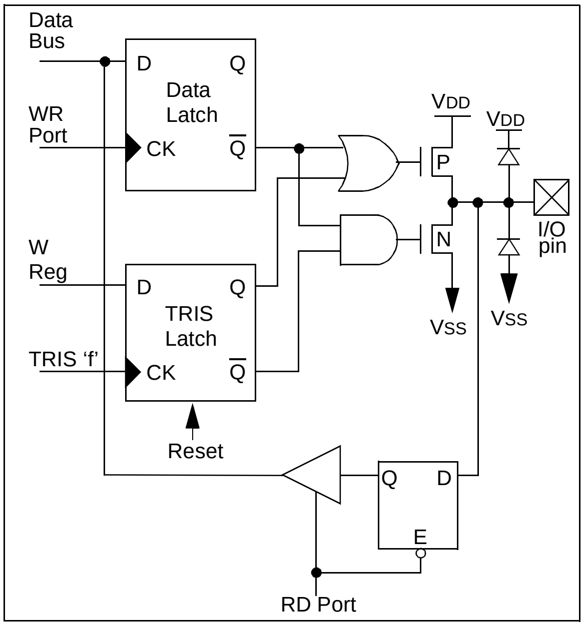


TABLE 6-1: SUMMARY OF PORT REGISTERS

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on Power-on Reset	Value on $\overline{\text{MCLR}}$ and WDT Reset
N/A	TRIS	I/O Control Registers (TRISA, TRISB, TRISC, TRISD and TRISE)								1111 1111	1111 1111
05h	PORTA	—	—	—	—	RA3	RA2	RA1	RA0	---- xxxx	---- uuuu
06h	PORTB	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0	xxxx xxxx	uuuu uuuu
07h	PORTC(1)	RC7	RC6	RC5	RC4	RC3	RC2	RC1	RC0	xxxx xxxx	uuuu uuuu
08h	PORTD(2)	RD7	RD6	RD5	RD4	RD3	RD2	RD1	RD0	xxxx xxxx	uuuu uuuu
09h	PORTE(2)	RE7	RE6	RE5	RE4	—	—	—	—	xxxx ----	uuuu ----

Legend: Shaded cells = unimplemented, read as '0', – = unimplemented, read as '0', x = unknown, u = unchanged

Note 1: File address 07h is a General Purpose Register on the PIC16F54.

2: File address 08h and 09h are General Purpose Registers on the PIC16F54 and PIC16F57.

6.8 I/O Programming Considerations

6.8.1 BIDIRECTIONAL I/O PORTS

Some instructions operate internally as read followed by write operations. The `BCF` and `BSF` instructions, for example, read the entire port into the CPU, execute the bit operation and re-write the result. Caution must be used when these instructions are applied to a port where one or more pins are used as input/outputs. For example, a `BSF` operation on bit 5 of PORTB will cause all eight bits of PORTB to be read into the CPU, bit 5 to be set and the PORTB value to be written to the output latches. If another bit of PORTB is used as a bidirectional I/O pin (say bit ‘`0`’), and it is defined as an input at this time, the input signal present on the pin itself would be read into the CPU and rewritten to the data latch of this particular pin, overwriting the previous content. As long as the pin stays in the Input mode, no problem occurs. However, if bit ‘`0`’ is switched into Output mode later on, the content of the data latch may now be unknown.

Example 6-1 shows the effect of two sequential read-modify-write instructions (e.g., `BCF`, `BSF`, etc.) on an I/O port.

A pin actively outputting a high or a low should not be driven from external devices at the same time in order to change the level on this pin (“wired-or”, “wired-and”). The resulting high output currents may damage the chip.

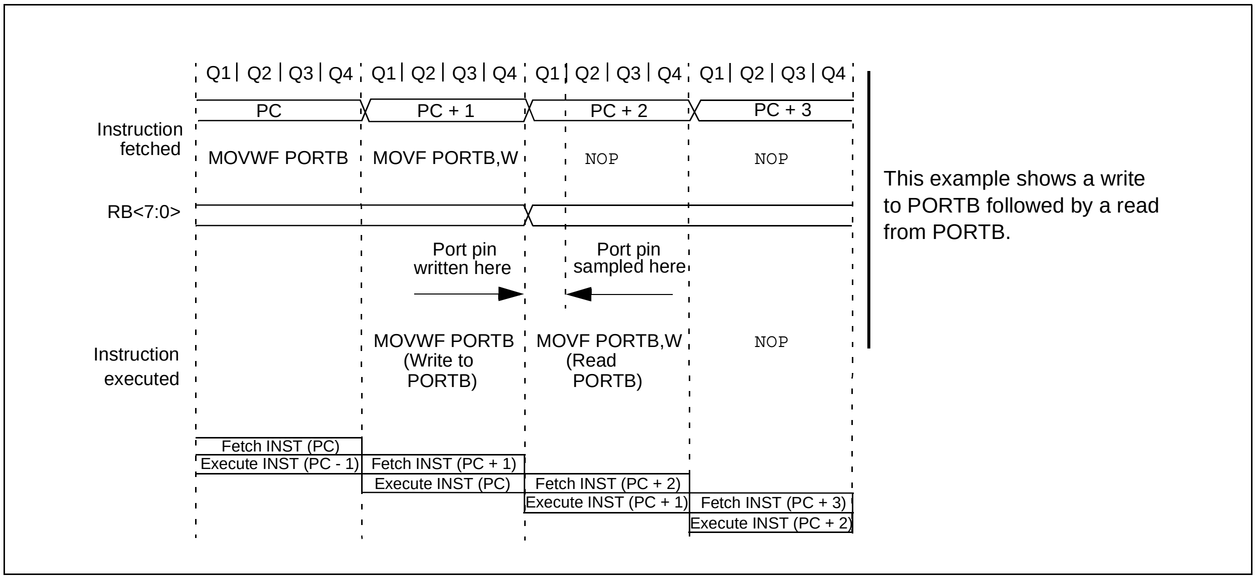
EXAMPLE 6-1: READ-MODIFY-WRITE INSTRUCTIONS ON AN I/O PORT

```
;Initial PORT Settings
;PORTB<7:4> Inputs
;PORTB<3:0> Outputs
;PORTB<7:6> have external pull-ups and are
;not connected to other circuitry
;
;                 PORT latch PORT pins
;                 --------------------
  BCF   PORTB, 7  ;01pp pppp   11pp pppp
  BCF   PORTB, 6  ;10pp pppp   11pp pppp
  MOVLW H'3F'     ;
  TRIS  PORTB     ;10pp pppp   10pp pppp
;
;Note that the user may have expected the
 pin
;values to be 00pp pppp. The 2nd BCF caused
;RB7 to be latched as the pin value (High).
```

6.8.2 SUCCESSIVE OPERATIONS ON I/O PORTS

The actual write to an I/O port happens at the end of an instruction cycle, whereas for reading, the data must be valid at the beginning of the instruction cycle (see Figure 6-2). Therefore, care must be exercised if a write followed by a read operation is carried out on the same I/O port. The sequence of instructions should allow the pin voltage to stabilize (load dependent) before the next instruction, which causes that file to be read into the CPU, is executed. Otherwise, the previous state of that pin may be read into the CPU rather than the new state. When in doubt, it is better to separate these instructions with a `NOP` or another instruction not accessing this I/O port.

FIGURE 6-2: SUCCESSIVE I/O OPERATION



This example shows a write to PORTB followed by a read from PORTB.

8.2 Watchdog Timer (WDT)

The Watchdog Timer (WDT) is a free running on-chip RC oscillator which does not require any external components. This RC oscillator is separate from the RC oscillator of the OSC1/CLKIN pin. That means that the WDT will run even if the clock on the OSC1/CLKIN and OSC2/CLKOUT pins have been stopped, for example, by execution of a `SLEEP` instruction. During normal operation or Sleep, a WDT Reset or Wake-up Reset generates a device Reset.

The $\overline{TO}$ bit (STATUS<4>) will be cleared upon a Watchdog Timer Reset (**Section 3.3 "STATUS Register"**).

The WDT can be permanently disabled by programming the Configuration bit WDTE as a '`0`' (**Section 8.1 "Configuration Bits"**). Refer to the PIC16F54 and PIC16F57 Programming Specifications to determine how to access the Configuration Word. These documents can be found on the Microchip web site at www.microchip.com.

8.2.1 WDT PERIOD

An 8-bit counter is available as a prescaler for the Timer0 module (**Section 7.2 "Prescaler"**), or as a postscaler for the Watchdog Timer (WDT), respectively. For simplicity, this counter is being referred to as "prescaler" throughout this data sheet.

Note:	The prescaler may be used by either the Timer0 module or the WDT, but not both. Thus, a prescaler assignment for the Timer0 module means that there is no prescaler for the WDT, and vice-versa.

The PSA and PS<2:0> bits (OPTION<3:0>) determine prescaler assignment and prescale ratio (**Section 3.4 "Option Register"**).

The WDT has a nominal time-out period of 18 ms (with no prescaler). If a longer time-out period is desired, a prescaler with a division ratio of up to 1:128 can be assigned to the WDT (under software control) by writing to the Option register. Thus time-out, a period of a nominal 2.3 seconds, can be realized. These periods vary with temperature, VDD and part-to-part process variations (see Device Characterization).

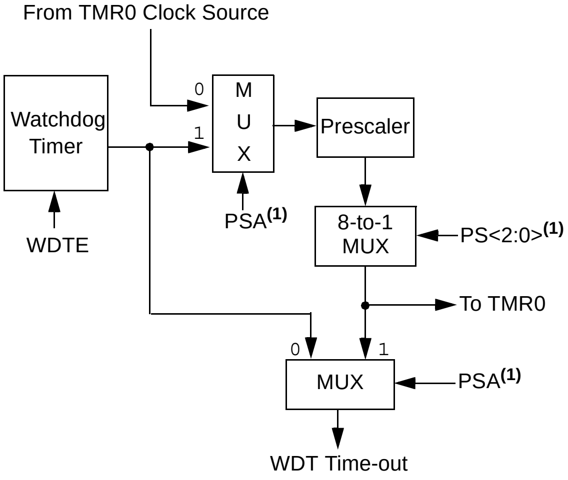
Under worst case conditions (VDD = Min., Temperature = Max., WDT prescaler = 1:128), it may take several seconds before a WDT time-out occurs.

8.2.2 WDT PROGRAMMING CONSIDERATIONS

The `CLRWDT` instruction clears the WDT and the prescaler, if assigned to the WDT, and prevents it from timing out and generating a device Reset.

The `SLEEP` instruction resets the WDT and the prescaler, if assigned to the WDT. This gives the maximum Sleep time before a WDT Wake-up Reset.

FIGURE 8-1: WATCHDOG TIMER BLOCK DIAGRAM



Note 1: T0CS, T0SE, PSA, PS<2:0> are bits in the Option register.

TABLE 8-1: SUMMARY OF REGISTERS ASSOCIATED WITH THE WATCHDOG TIMER

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on Power-on Reset	Value on $\overline{MCLR}$ and WDT Reset
N/A	OPTION	—	—	T0CS	T0SE	PSA	PS2	PS1	PS0	`--11 1111`	`--11 1111`

Legend: Shaded cells not used by Watchdog Timer, `-` = unimplemented, read as '`0`', `u` = unchanged

ADDWF Add W and f

Syntax:	[*label*] ADDWF f, d
Operands:	$0 \le f \le 31$ $d \in [0,1]$
Operation:	(W) + (f) → (dest)
Status Affected:	C, DC, Z
Encoding:	`0001` `11df` `ffff`
Description:	Add the contents of the W register and register ‘f’. If ‘d’ is ‘`0`’, the result is stored in the W register. If ‘d’ is ‘`1`’, the result is stored back in register ‘f’.
Words:	`1`
Cycles:	`1`
Example:	`ADDWF TEMP_REG, 0`

Before Instruction
W = 0x17
TEMP_REG = 0xC2
After Instruction
W = 0xD9
TEMP_REG = 0xC2

ANDLW AND literal with W

Syntax:	[*label*] ANDLW k
Operands:	$0 \le k \le 255$
Operation:	(W).AND. (k) → (W)
Status Affected:	Z
Encoding:	`1110` `kkkk` `kkkk`
Description:	The contents of the W register are AND’ed with the eight-bit literal ‘k’. The result is placed in the W register.
Words:	1
Cycles:	1
Example:	`ANDLW H'5F'`

Before Instruction
W = 0xA3
After Instruction
W = 0x03

ANDWF AND W with f

Syntax:	[*label*] ANDWF f, d
Operands:	$0 \le f \le 31$ $d \in [0,1]$
Operation:	(W) .AND. (f) → (dest)
Status Affected:	Z
Encoding:	`0001` `01df` `ffff`
Description:	The contents of the W register are AND’ed with register ‘f’. If ‘d’ is ‘`0`’, the result is stored in the W register. If ‘d’ is ‘`1`’, the result is stored back in register ‘f’.
Words:	1
Cycles:	1
Example:	`ANDWF TEMP_REG, 1`

Before Instruction
W = 0x17
TEMP_REG = 0xC2
After Instruction
W = 0x17
TEMP_REG = 0x02

BCF Bit Clear f

Syntax:	[*label*] BCF f, b
Operands:	$0 \le f \le 31$ $0 \le b \le 7$
Operation:	0 → (f<b>)
Status Affected:	None
Encoding:	`0100` `bbbf` `ffff`
Description:	Bit ‘b’ in register ‘f’ is cleared.
Words:	1
Cycles:	1
Example:	`BCF FLAG_REG, 7`

Before Instruction
FLAG_REG = 0xC7
After Instruction
FLAG_REG = 0x47

CALL	**Subroutine Call**
Syntax:	[*label*] CALL k
Operands:	$0 \leq k \leq 255$
Operation:	(PC) + 1→ TOS; k → PC<7:0>; (Status<6:5>) → PC<10:9>; 0 → PC<8>
Status Affected:	None
Encoding:	`1001` `kkkk` `kkkk`
Description:	Subroutine call. First, return address (PC + 1) is pushed onto the stack. The eight-bit immediate address is loaded into PC bits <7:0>. The upper bits PC<10:9> are loaded from STATUS<6:5>, PC<8> is cleared. `CALL` is a two-cycle instruction.
Words:	1
Cycles:	2
Example:	`HERE CALL THERE`

Before Instruction
PC = address `(HERE)`
After Instruction
PC = address `(THERE)`
TOS = address `(HERE + 1)`

CLRF	**Clear f**
Syntax:	[*label*] CLRF f
Operands:	$0 \leq f \leq 31$
Operation:	00h → (f); 1 → Z
Status Affected:	Z
Encoding:	`0000` `011f` `ffff`
Description:	The contents of register 'f' are cleared and the Z bit is set.
Words:	1
Cycles:	1
Example:	`CLRF FLAG_REG`

Before Instruction
FLAG_REG = 0x5A
After Instruction
FLAG_REG = 0x00
Z = 1

CLRW	**Clear W**
Syntax:	[*label*] CLRW
Operands:	None
Operation:	00h → (W); 1 → Z
Status Affected:	Z
Encoding:	`0000` `0100` `0000`
Description:	The W register is cleared. Zero bit (Z) is set.
Words:	1
Cycles:	1
Example:	`CLRW`

Before Instruction
W = 0x5A
After Instruction
W = 0x00
Z = 1

CLRWDT	**Clear Watchdog Timer**
Syntax:	[*label*] CLRWDT
Operands:	None
Operation:	00h → WDT; 0 → WDT prescaler (if assigned); 1 → $\overline{\text{TO}}$; 1 → $\overline{\text{PD}}$
Status Affected:	$\overline{\text{TO}}$, $\overline{\text{PD}}$
Encoding:	`0000` `0000` `0100`
Description:	The `CLRWDT` instruction resets the WDT. It also resets the prescaler if the prescaler is assigned to the WDT and not Timer0. Status bits $\overline{\text{TO}}$ and $\overline{\text{PD}}$ are set.
Words:	1
Cycles:	1
Example:	`CLRWDT`

Before Instruction
WDT counter = ?
After Instruction
WDT counter = 0x00
WDT prescaler = 0
$\overline{\text{TO}}$ = 1
$\overline{\text{PD}}$ = 1

RLF — Rotate Left f through Carry

Syntax:	[*label*] RLF f, d
Operands:	$0 \le f \le 31$ $d \in [0,1]$
Operation:	See description below
Status Affected:	C
Encoding:	`0011` `01df` `ffff`
Description:	The contents of register ‘f’ are rotated one bit to the left through the Carry Flag (STATUS<0>). If ‘d’ is ‘`0`’, the result is placed in the W register. If ‘d’ is ‘`1`’, the result is stored back in register ‘f’.

Words:	1
Cycles:	1
Example:	`RLF REG1,0`

Before Instruction

REG1 = `1110 0110`

C = `0`

After Instruction

REG1 = `1110 0110`

W = `1100 1100`

C = `1`

RRF — Rotate Right f through Carry

Syntax:	[*label*] RRF f, d
Operands:	$0 \le f \le 31$ $d \in [0,1]$
Operation:	See description below
Status Affected:	C
Encoding:	`0011` `00df` `ffff`
Description:	The contents of register ‘f’ are rotated one bit to the right through the Carry Flag (STATUS<0>). If ‘d’ is ‘`0`’, the result is placed in the W register. If ‘d’ is ‘`1`’, the result is placed back in register ‘f’.

Words:	1
Cycles:	1
Example:	`RRF REG1,0`

Before Instruction

REG1 = `1110 0110`

C = `0`

After Instruction

REG1 = `1110 0110`

W = `0111 0011`

C = `0`

Sleep — Go into Standby Mode

Syntax:	[*label*] Sleep
Operands:	None
Operation:	00h → WDT; 0 → WDT prescaler; if assigned 1 → $\overline{\text{TO}}$; 0 → $\overline{\text{PD}}$
Status Affected:	$\overline{\text{TO}}$, $\overline{\text{PD}}$
Encoding:	`0000` `0000` `0011`
Description:	Time-out Status bit ($\overline{\text{TO}}$) is set. The power-down Status bit ($\overline{\text{PD}}$) is cleared. The WDT and its prescaler are cleared. The processor is put into Sleep mode with the oscillator stopped. See section on Sleep for more details.
Words:	1
Cycles:	1
Example:	`SLEEP`

10.11 PICSTART Plus Development Programmer

The PICSTART Plus Development Programmer is an easy-to-use, low-cost, prototype programmer. It connects to the PC via a COM (RS-232) port. MPLAB Integrated Development Environment software makes using the programmer simple and efficient. The PICSTART Plus Development Programmer supports most PIC devices in DIP packages up to 40 pins. Larger pin count devices, such as the PIC16C92X and PIC17C76X, may be supported with an adapter socket. The PICSTART Plus Development Programmer is CE compliant.

10.12 PICkit 2 Development Programmer

The PICkit™ 2 Development Programmer is a low-cost programmer and selected Flash device debugger with an easy-to-use interface for programming many of Microchip's baseline, mid-range and PIC18F families of Flash memory microcontrollers. The PICkit 2 Starter Kit includes a prototyping development board, twelve sequential lessons, software and HI-TECH's PICC™ Lite C compiler, and is designed to help get up to speed quickly using PIC® microcontrollers. The kit provides everything needed to program, evaluate and develop applications using Microchip's powerful, mid-range Flash memory family of microcontrollers.

10.13 Demonstration, Development and Evaluation Boards

A wide variety of demonstration, development and evaluation boards for various PIC MCUs and dsPIC DSCs allows quick application development on fully functional systems. Most boards include prototyping areas for adding custom circuitry and provide application firmware and source code for examination and modification.

The boards support a variety of features, including LEDs, temperature sensors, switches, speakers, RS-232 interfaces, LCD displays, potentiometers and additional EEPROM memory.

The demonstration and development boards can be used in teaching environments, for prototyping custom circuits and for learning about various microcontroller applications.

In addition to the PICDEM™ and dsPICDEM™ demonstration/development board series of circuits, Microchip has a line of evaluation kits and demonstration software for analog filter design, KEELOQ® security ICs, CAN, IrDA®, PowerSmart® battery management, SEEVAL® evaluation system, Sigma-Delta ADC, flow rate sensing, plus many more.

Check the Microchip web page (www.microchip.com) and the latest *"Product Selector Guide"* (DS00148) for the complete list of demonstration, development and evaluation kits.

11.0 ELECTRICAL SPECIFICATIONS FOR PIC16F54/57

Absolute Maximum Ratings$^{(\dagger)}$

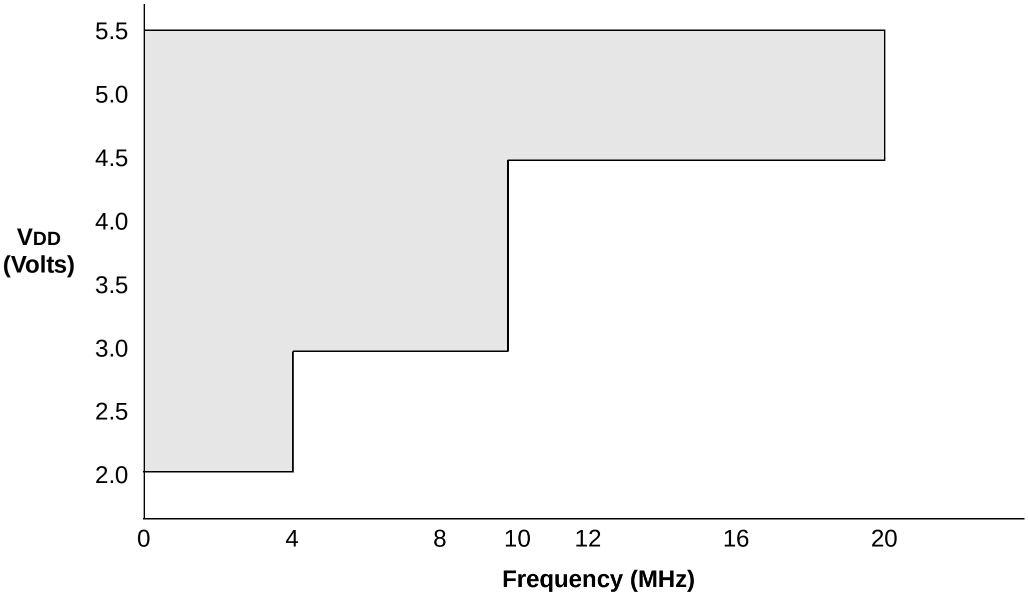
Ambient Temperature under bias	-40°C to +125°C
Storage Temperature	-65°C to +150°C
Voltage on V_{DD} with respect to V_{SS}	0V to +6.5V
Voltage on $\overline{\text{MCLR}}$ with respect to $V_{SS}$$^{(1)}$	0V to +13.5V
Voltage on all other pins with respect to V_{SS}	-0.6V to (V_{DD} + 0.6V)
Total power dissipation$^{(2)}$	800 mW
Max. current out of V_{SS} pin	150 mA
Max. current into V_{DD} pin	100 mA
Max. current into an input pin (T0CKI only)	±500 μA
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{DD}$)	±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{DD}$)	±20 mA
Max. output current sunk by any I/O pin	25 mA
Max. output current sourced by any I/O pin	25 mA
Max. output current sourced by a single I/O port (PORTA, B or C)	50 mA
Max. output current sunk by a single I/O port (PORTA, B or C)	50 mA

Note 1: Voltage spikes below V_{SS} at the $\overline{\text{MCLR}}$ pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50 to 100Ω should be used when applying a "low" level to the $\overline{\text{MCLR}}$ pin rather than pulling this pin directly to V_{SS}.

2: Power Dissipation is calculated as follows: $P_{dis} = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD} - V_{OH}) \times I_{OH}\} + \sum(V_{OL} \times I_{OL})$

†NOTICE: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

FIGURE 11-1: PIC16F5X VOLTAGE-FREQUENCY GRAPH, -40°C ≤ T_A ≤ +125°C



Note 1: The shaded region indicates the permissible combinations of voltage and frequency.

11.1 DC Characteristics: PIC16F5X (Industrial)

<table>
<tr><th colspan="3">DC CHARACTERISTICS</th><th colspan="5">Standard Operating Conditions (unless otherwise specified)
Operating Temperature -40°C ≤ TA ≤ +85°C for industrial</th></tr>
<tr><th>Param No.</th><th>Sym.</th><th>Characteristic/Device</th><th>Min.</th><th>Typ†</th><th>Max.</th><th>Units</th><th>Conditions</th></tr>
<tr><td>D001</td><td>VDD</td><td>Supply Voltage</td><td>2.0</td><td>—</td><td>5.5</td><td>V</td><td></td></tr>
<tr><td>D002</td><td>VDR</td><td>RAM Data Retention Voltage(1)</td><td>—</td><td>1.5*</td><td>—</td><td>V</td><td>Device in Sleep mode</td></tr>
<tr><td>D003</td><td>VPOR</td><td>VDD Start Voltage to ensure Power-on Reset</td><td>—</td><td>Vss</td><td>—</td><td>V</td><td>See Section 5.1 “Power-on Reset (POR)” for details on Power-on Reset</td></tr>
<tr><td>D004</td><td>SVDD</td><td>VDD Rise Rate to ensure Power-on Reset</td><td>0.05*</td><td>—</td><td>—</td><td>V/ms</td><td>See Section 5.1 “Power-on Reset (POR)” for details on Power-on Reset</td></tr>
<tr><td rowspan="5">D010</td><td rowspan="5">IDD</td><td colspan="6">Supply Current(2)</td></tr>
<tr><td rowspan="4"></td><td>—</td><td>170</td><td>350</td><td>µA</td><td>FOSC = 4 MHz, VDD = 2.0V, XT or RC mode(3)</td></tr>
<tr><td>—</td><td>0.4</td><td>1.0</td><td>mA</td><td>FOSC = 10 MHz, VDD = 3.0V, HS mode</td></tr>
<tr><td>—</td><td>1.7</td><td>5.0</td><td>mA</td><td>FOSC = 20 MHz, VDD = 5.0V, HS mode</td></tr>
<tr><td>—</td><td>15</td><td>22.5</td><td>µA</td><td>FOSC = 32 kHz, VDD = 2.0V, LP mode, WDT disabled</td></tr>
<tr><td rowspan="3">D020</td><td rowspan="3">IPD</td><td colspan="6">Power-down Current(2)</td></tr>
<tr><td rowspan="2"></td><td>—</td><td>1.0</td><td>6.0</td><td>µA</td><td>VDD = 2.0V, WDT enabled</td></tr>
<tr><td>—</td><td>0.5</td><td>2.5</td><td>µA</td><td>VDD = 2.0V, WDT disabled</td></tr>
</table>

* These parameters are characterized but not tested.

† Data in “Typ” column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: This is the limit to which VDD can be lowered in Sleep mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature, also have an impact on the current consumption.

a) The test conditions for all IDD measurements in Active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VSS, T0CKI = VDD, $\overline{\text{MCLR}}$ = VDD; WDT enabled/disabled as specified.

b) For standby current measurements, the conditions are the same, except that the device is in Sleep mode. The Power-down Current in Sleep mode does not depend on the oscillator type.

3: Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in kΩ.

11.2 DC Characteristics: PIC16F5X (Extended)

DC CHARACTERISTICS			**Standard Operating Conditions (unless otherwise specified)** Operating Temperature -40°C ≤ TA ≤ +125°C for extended				
Param No.	**Sym.**	**Characteristic/Device**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
D001	VDD	**Supply Voltage**	2.0	—	5.5	V	
D002	VDR	**RAM Data Retention Voltage(1)**	—	1.5*	—	V	Device in Sleep mode
D003	VPOR	**VDD Start Voltage** to ensure Power-on Reset	—	VSS	—	V	See **Section 5.1 "Power-on Reset (POR)"** for details on Power-on Reset
D004	SVDD	**VDD Rise Rate** to ensure Power-on Reset	0.05*	—	—	V/ms	See **Section 5.1 "Power-on Reset (POR)"** for details on Power-on Reset
D010	IDD	**Supply Current(2)**					
			—	170	450	µA	FOSC = 4 MHz, VDD = 2.0V, XT or RC mode(3)
			—	0.4	2.0	mA	FOSC = 10 MHz, VDD = 3.0V, HS mode
			—	1.7	7.0	mA	FOSC = 20 MHz, VDD = 5.0V, HS mode
			—	15	40	µA	FOSC = 32 kHz, VDD = 2.0V, LP mode, WDT disabled
D020	IPD	**Power-down Current(2)**					
			—	1.0	15.0	µA	VDD = 2.0V, WDT enabled
			—	0.5	8.0	µA	VDD = 2.0V, WDT disabled

* These parameters are characterized but not tested.

† Data in "Typ" column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: This is the limit to which VDD can be lowered in Sleep mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature, also have an impact on the current consumption.

a) The test conditions for all IDD measurements in Active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VSS, T0CKI = VDD, $\overline{\text{MCLR}}$ = VDD; WDT enabled/disabled as specified.

b) For standby current measurements, the conditions are the same, except that the device is in Sleep mode. The Power-down Current in Sleep mode does not depend on the oscillator type.

3: Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in kΩ.

11.3 DC Characteristics PIC16F5X

DC CHARACTERISTICS	**Standard Operating Conditions (unless otherwise specified)** Operating Temperature -40°C ≤ T_A ≤ +85°C for industrial -40°C ≤ T_A ≤ +125°C for extended

Param No.	Sym.	Characteristic	Min.	Typ†	Max.	Units	Conditions
	V_{IL}	**Input Low Voltage**					
D030		I/O Ports	V_{SS}	—	0.8V	V	4.5V < V_{DD} ≤ 5.5V
		I/O Ports	V_{SS}	—	0.15 V_{DD}	V	V_{DD} ≤ 4.5V
		$\overline{\text{MCLR}}$ (Schmitt Trigger)	V_{SS}	—	0.15 V_{DD}	V	
		T0CKI (Schmitt Trigger)	V_{SS}	—	0.15 V_{DD}	V	
		OSC1 (Schmitt Trigger)	V_{SS}	—	0.15 V_{DD}	V	RC mode(3)
		OSC1	V_{SS}	—	0.3 V_{DD}	V	HS mode
			V_{SS}	—	0.3	V	XT mode
			V_{SS}	—	0.3	V	LP mode
	V_{IH}	**Input High Voltage**					
D040		I/O ports	2.0	—	V_{DD}	V	4.5V < V_{DD} ≤ 5.5V
		I/O ports	0.25 V_{DD} + 0.8	—	V_{DD}	V	V_{DD} ≤ 4.5V
		$\overline{\text{MCLR}}$ (Schmitt Trigger)	0.85 V_{DD}	—	V_{DD}	V	
		T0CKI (Schmitt Trigger)	0.85 V_{DD}	—	V_{DD}	V	
		OSC1 (Schmitt Trigger)	0.85 V_{DD}	—	V_{DD}	V	RC mode(3)
		OSC1	0.7 V_{DD}	—	V_{DD}	V	HS mode
			1.6	—	V_{DD}	V	XT mode
			1.6	—	V_{DD}	V	LP mode
	I_{IL}	**Input Leakage Current(1, 2)**					
D060		I/O ports	—	—	±1.0	μA	V_{SS} ≤ V_{PIN} ≤ V_{DD}, pin at high-impedance
		$\overline{\text{MCLR}}$	—	—	±5.0	μA	V_{SS} ≤ V_{PIN} ≤ V_{DD}
		T0CKI	—	—	±5.0	μA	V_{SS} ≤ V_{PIN} ≤ V_{DD}
		OSC1	—	—	±5.0	μA	V_{SS} ≤ V_{PIN} ≤ V_{DD}, XT, HS and LP modes
	V_{OL}	**Output Low Voltage**					
D080		I/O ports	—	—	0.6	V	I_{OL} = 8.5 mA, V_{DD} = 4.5V
D083		OSC2/CLKOUT (RC mode)	—	—	0.6	V	I_{OL} = 1.6 mA, V_{DD} = 4.5V
	V_{OH}	**Output High Voltage(2)**					
D090		I/O ports(2)	V_{DD} – 0.7	—	—	V	I_{OH} = -3.0 mA, V_{DD} = 4.5V
D092		OSC2/CLKOUT (RC mode)	V_{DD} – 0.7	—	—	V	I_{OH} = -1.3 mA, V_{DD} = 4.5V

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: The leakage current on the $\overline{\text{MCLR}}$/V_{PP} pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltage.

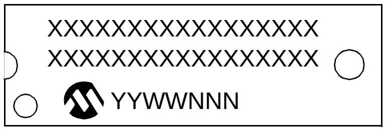
2: Negative current is defined as coming out of the pin.

3: For the RC mode, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16F5X be driven with external clock in RC mode.

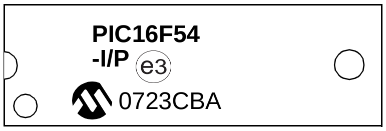
12.0 PACKAGING INFORMATION

12.1 Package Marking Information

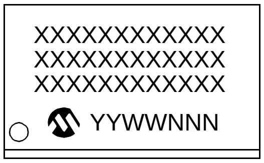
18-Lead PDIP



Example

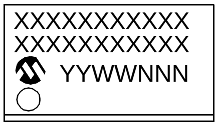


18-Lead SOIC

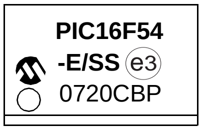


Example

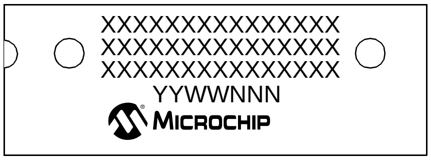
20-Lead SSOP



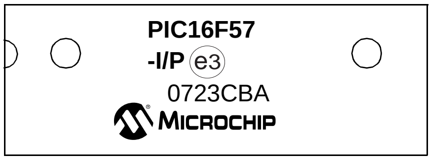
Example



28-Lead PDIP



Example



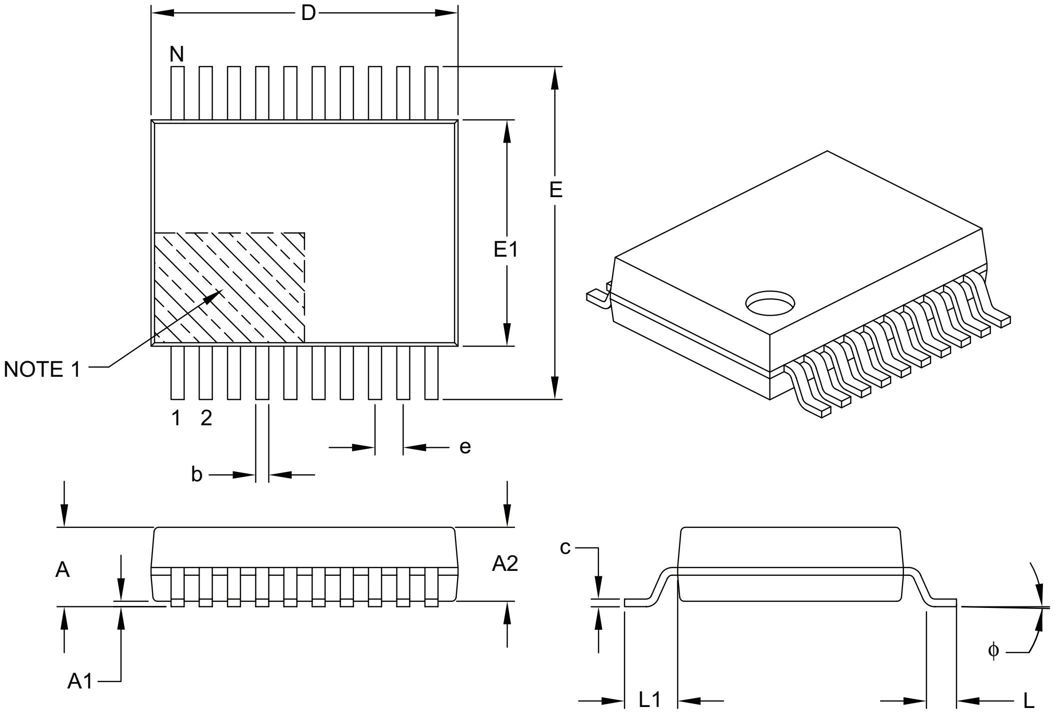
Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week ‘01’)
	NNN	Alphanumeric traceability code
	e3	Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

***** Standard PIC device marking consists of Microchip part number, year code, week code, and traceability code. For PIC device marking beyond this, certain price adders apply. Please check with your Microchip Sales Office. For QTP devices, any special marking adders are included in QTP price.

20-Lead Plastic Shrink Small Outline (SS) – 5.30 mm Body [SSOP]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



		Units	MILLIMETERS		
		Dimension Limits	MIN	NOM	MAX
Number of Pins	N		20		
Pitch	e		0.65 BSC		
Overall Height	A		–	–	2.00
Molded Package Thickness	A2		1.65	1.75	1.85
Standoff	A1		0.05	–	–
Overall Width	E		7.40	7.80	8.20
Molded Package Width	E1		5.00	5.30	5.60
Overall Length	D		6.90	7.20	7.50
Foot Length	L		0.55	0.75	0.95
Footprint	L1		1.25 REF		
Lead Thickness	c		0.09	–	0.25
Foot Angle	ϕ		0°	4°	8°
Lead Width	b		0.22	–	0.38

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.20 mm per side.
3. Dimensioning and tolerancing per ASME Y14.5M.
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.

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3. Do you find the organization of this document easy to follow? If not, why?

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4. What additions to the document do you think would enhance the structure and subject?

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5. What deletions from the document could be made without affecting the overall usefulness?

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